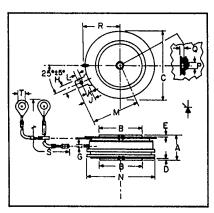




Phase Control SCR 800 Amperes Avg 100-600 Volts



C430\_X500 Outline Drawing

	Inches		Millimeters	
Dimensions	Min.	Max.	Min.	Max.
_A	.560	.605	14.22	15.37
B	.985	.995	25.01	25.27
С	1.600	1.650	40.64	41.91
D	.030	_	.76	
E	.040	_	1.01	_
G	.057	.059	1.44	1.50
Н	.186	.191	4.72	4.85
J	.245	.255	6.22	6.48
K	.115	.130	2.92	3.30
L	.064	.070	1.62	1.78
М	_	1.120	_	28.45
N	_	1.585	_	40.26
Р	.135	.145	3.42	3.68
Q	.070	.084	1.77	2.13
R	_	.875		22.23
S	12.219	12.343	310.36	313.51
T	.137	.153	3.47	3,89



C430\_\_X500 Phase Control SCR 800 Amperes/100-600 Volts

### Description

Powerex Silicon Controlled Rectifiers (SCR) are designed for phase control applications. These are all-diffused, Press-Pak (Pow-R-Disc) devices employing the field-proven amplifying (di/namic) gate.

#### Features:

- □ Low On-State Voltage
- ☐ High di/dt
- ☐ High dv/dt
- ☐ Hermetic Packaging
- ☐ Excellent Surge and I2t Ratings

#### Applications:

- ☐ Power Supplies
- ☐ Battery Chargers
- ☐ Motor Control
- □ Light Dimmers
- ☐ VAR Generators

### **Ordering Information**

Example: Select the complete nine digit part number you desire from the table – i.e. C430DX500 is a 400 Volt, 800 Ampere Phase Control SCR.

Туре	Voltage		Current
	VDRM VRRM	Code	IT (avg)
C430X500	100	Α	800
	200	В	]
	300	С	]
	400	D	
[	500	E	
	600	М	



POWEREX INC

Powerex, Inc., Hillis Street, Youngwood, Pennsylvania 15897 (412) 925-7272 Powerex Europe, S.A., 428 Ave. G. Durand, BP107, 72003 LeMans, France (43) 72.75.15

C430....X500 Phase Control SCR 800 Amperes Avg/100-600 Volts

# **Absolute Maximum Ratings**

	Symbol	C430X500	Units
RMS On-State Current	I <sub>T(FIMS)</sub>	1250	Amperes
Average On-State Current	I <sub>T(ev)</sub>	800	<del></del>
Peak One-Cycle Surge (Non-Repetitive) On-State Current (60Hz)	TSM	10,000	Amperes Amperes
Peak One-Cycle Surge (Non-Repetitive) On-State Current (50Hz)	I <sub>TSM</sub>	9125	
Critical Rate-of-Rise of On-State Current (Non-Repetitive)	di/dt	400	Amperes
Critical Rate-of-Rise of On-State Current (Repetitive)	di/dt	150	Amperes/μs
I²t (for Fusing), One Cycle at 60Hz	l <sup>2</sup> t	415,000	Amperes/μs
Peak Gate Power Dissipation	P <sub>GM</sub>	200	A <sup>2</sup> sec
Average Gate Power Dissipation	P <sub>G(ev)</sub>	5	Watts
Storage Temperature			Watts
Operating Temperature	T <sub>STG</sub>	-40 to 150	<u>•c</u>
Mounting Force®	T,	-40 to 125	<u>•c</u>
	· · · · · · · · · · · · · · · · · · ·	800 to 2200	lb.
Mounting Force <sup>®</sup>		3.6 to 11.1	kN

① Consult recommended mounting procedures.



02

C430....X500 Phase Control SCR 800 Amperes Avg/100-600 Volts

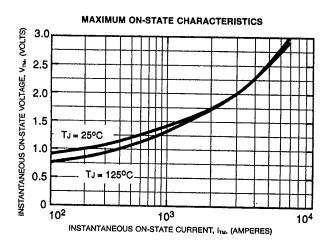
## **Electrical and Thermal Characteristics**

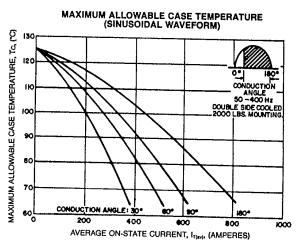
Characteristics	Symbol	Test Conditions	C438X500	Units
Voltage—Blocking State Maximums				
Forward Leakage, Peak	I <sub>DRM</sub>	$T_J = 125^{\circ}C, V = V_{DRM}$	45	mA
Reverse Leakage, Peak	I <sub>RRM</sub>	$T_J = 125^{\circ}C, V = V_{RRM}$	45	mA
Current—Conducting State Maximums Peak On-State Voltage	V <sub>TM</sub>	! <sub>TM</sub> = 3000A, T <sub>C</sub> = 25°C	1.9	Volts
Switching Typical Turn-Off Time	t <sub>q</sub>	T <sub>J</sub> = 125°C, I <sub>TM</sub> = 500A; V <sub>R</sub> = 50V Min; V <sub>DRM</sub> (Reapplied); Reapplied dv/dt = 20V/μsec (linear); Commutation dl/dt = 25A/μsec; Repetition Rate = 1pps; Gate Bias during Turn-Off interval = 0V, 100Ω	100	нзес
Typical Delay Time	t <sub>d</sub>	$T_C = 25^{\circ}C$ , $I_T = 50A$ ; Gate Supply: 25 Volts, $20\Omega$ , 0.1 µsec rise time	0.7	µsес
Min. Critical dv/dt exponential to VDRM	dv/dt	T <sub>J</sub> = 125°C, V <sub>DRM</sub> rated, gate open	200	V/µsec
Thermal  Maximum Thermal Resistance, <sup>©</sup> double sided cooling  Junction to Case (2000 lb. force)	R <sub>exc</sub>		.04	*C/Watt
Case to Sink, Lubricated (2000 lb. force)	R <sub>ecs</sub>		.02	*C/Watt
Gate—Maximum Parameters Gate Current to Trigger	l <sub>er</sub>	V <sub>D</sub> = 6Vdc, R <sub>L</sub> = 3Ω, T <sub>J</sub> = 25°C	125	mA
Gate Voltage to Trigger	V <sub>GT</sub>	$T_J = -40^{\circ}C$ to 125°C, $V_D = 6Vdc$ , $R_L = 3\Omega$	5	Volts
Non-Triggering Gate Voltage	V <sub>GDM</sub>	$T_J = 125$ °C, rated $V_{DRM}$	.15	Volts
Peak Forward Gate Current	I <sub>GTM</sub>		4	Amperes
Peak Reverse Gate Voltage	V <sub>GRM</sub>		5	Volts

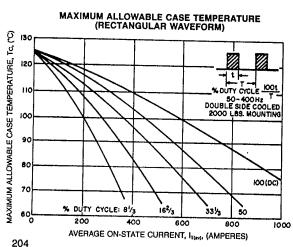
① Consult recommended mounting procedures.

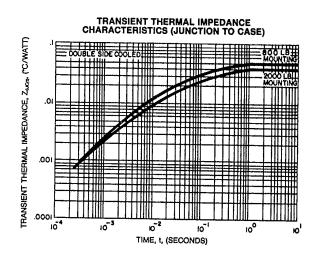


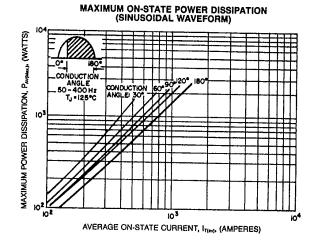
C430....X500 Phase Control SCR 800 Amperes Avg/100-600 Volts

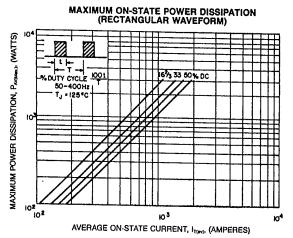










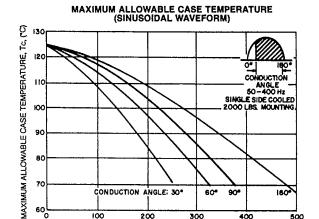






C430\_\_X500 Phase Control SCR 800 Amperes Avg/100-600 Volts

100

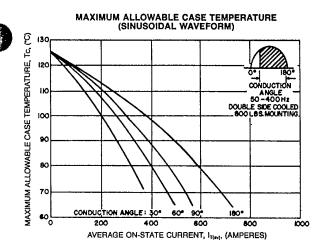


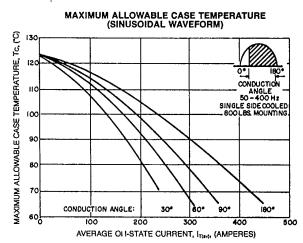
200

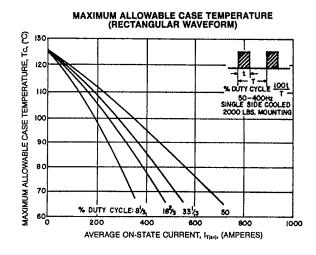
300

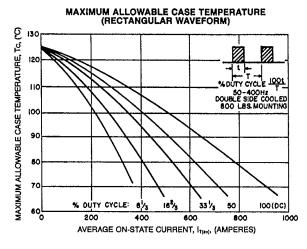
AVERAGE ON-STATE CURRENT, IT(sx), (AMPERES)

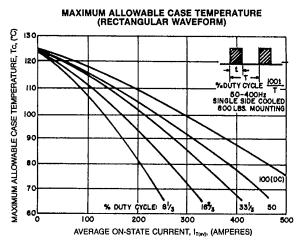
500







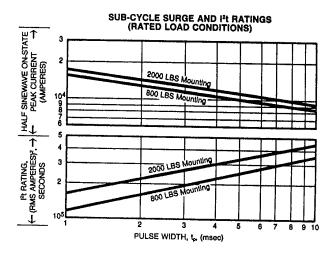


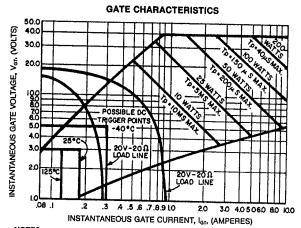




02

C430\_\_X500 Phase Control SCR 800 Amperes Avg/100-600 Volts





### NOTES:

- NOTES:

  1. Maximum allowable average gate dissipation = 5 watts.

  2. The locus of possible dc trigger points lie outside the boundaries shown at various case temperatures.

  3. Tp = Rectangular gate current pulse width (5μs min. duration; 1.0μs max. rise time for 20V, 65Ω source).

  4. 20V 20Ω is the minimum gate source load line when rate of circuit current rise > 100 Amp/us or anode rate of current rise > 200 Amps/μs (Tp = 5μs min., 0.5μs max. rise time).

Maximum long-term repetitive anode di/dt  $\approx$  500 Amps/ $\mu s$  with 20V - 20 $\Omega$  gate source.